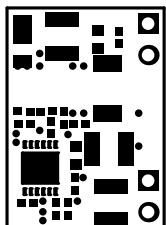
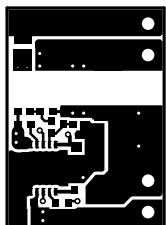


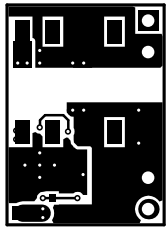
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10736	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP10736		
PLOT NAME = Top Overlay	GENERATED : 8/15/2015 11:57:52 PM	TEXAS INSTRUMENTS	



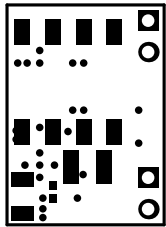
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LAYER NAME = Top Solder	TID #: PMP10736		
PLOT NAME = Top Solder Mask	GENERATED : 8/15/2015 11:57:53 PM	TEXAS INSTRUMENTS	



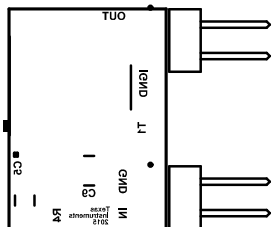
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10736	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP10736		
PLOT NAME = Top Layer	GENERATED : 8/15/2015 11:57:53 PM	TEXAS INSTRUMENTS	



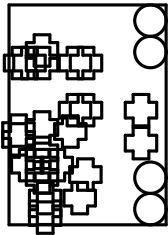
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10736	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP10736		
PLOT NAME = Bottom Layer	GENERATED : 8/15/2015 11:57:54 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10736	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP10736		
PLOT NAME = Bottom Solder Mask	GENERATED : 8/15/2015 11:57:55 PM	TEXAS INSTRUMENTS	

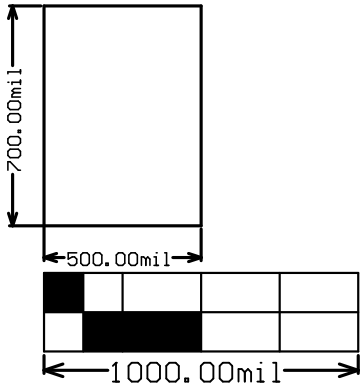


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10736	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP10736		
PLOT NAME = Bottom Overlay	GENERATED : 8/15/2015	11:57:55 PM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
⊕	24	10.00mil (0.254mm)	PTH	Round
○	4	39.37mil (1.000mm)	PTH	Round
	28 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10736	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP10736		
PLOT NAME = Drill Drawing	GENERATED : 8/15/2015	11:57:56 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10736	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP10736		
PLOT NAME = Board Dimensions	GENERATED : 8/15/2015	11:57:56 PM	TEXAS INSTRUMENTS

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